



Patent

Applicants: VANDENTOP et al.

Application No.: 10/667,694

Filing Date: 9/22/2003

For: INTEGRATED CIRCUIT  
DIE/PACKAGE INTERCONNECT

- ) Confirmation No.: 9242
- )
- ) Group Art Unit: 2841
- )
- ) Examiner: Tuan T. Dinh
- )
- ) **AMENDMENT and RESPONSE to**
- ) September 20, 2006 Non-Final Office Action
- )
- ) Attorney Docket No.: P16922
- )
- ) **PTO Customer Number 28062**
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**CERTIFICATE OF MAILING UNDER 37 CFR 1.8**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 20, 2006.

Dated: November 20, 2006

By:

  
Edith Martin

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Non-Final Office Action mailed September 20, 2006, please amend the above-identified application as follows:

**Amendments to the claims** are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 8 of this paper.